IN THE CLAIMS:

1. (Currently Amended) A method for mounting a flexible substrate during the fabrication of a liquid crystal display (LCD), the method comprising:

forming a first rigid support substrate with trenches;

forming a first flexible substrate overlying the first rigid support substrate;

injecting adhesive into the <u>trenches of the</u> first rigid support substrate trenches; and

curing the adhesive to attach the first flexible substrate to the first <u>rigid</u> support substrate.

2. (Currently Amended) The method of claim 1 further comprising:

subsequent to additional LCD fabrication processes, detaching the first <u>rigid</u> support substrate and adhesive from the first flexible substrate.

3. (Original) The method of claim 1 further comprising:

depositing a plurality of patterned integrated circuit films overlying the first flexible substrate, forming thin film transistors (TFTs); forming a liquid crystal (LC) layer overlying the TFTs; and, forming a color filter layer over the LC layer.

4. (Currently Amended) The method of claim 3 further comprising:

forming a second flexible substrate overlying the color filter; forming a second rigid support substrate with trenches overlying the second flexible substrate;

injecting adhesive into the <u>trenches of the</u> second rigid support substrate trenches; and

curing the adhesive to attach the second flexible substrate to the second <u>rigid</u> support substrate.

- 5. (Currently Amended) The method of claim 1 wherein injecting adhesive into the <u>trenches of the</u> first rigid support substrate trenches includes injecting the adhesive in a vacuum environment.
- 6. (Currently Amended) The method of claim 5 wherein forming a first rigid support substrate with trenches includes forming trenches with at least one trench mouth;

wherein injecting adhesive into the <u>trenches of the</u> first support substrate trenches includes:

creating a vacuum environment in the first rigid support substrate trenches;

supplying adhesive to the at least one mouth of the first rigid support substrate trenches;

in response to returning the first rigid support substrate to ambient pressure, pulling the adhesive into the first rigid support substrate trenches vacuum environment through the at least one mouth.

- 7. (Original) The method of claim 6 wherein returning the first rigid support substrate to ambient pressure includes supplying an N2 atmosphere at ambient pressure.
- 8. (Original) The method of claim 1 wherein forming the first rigid support substrate with trenches includes forming a rigid support substrate from a material selected from the group including glass and plastic.
- 9. (Original) The method of claim 1 wherein forming the first flexible substrate overlying the first rigid support substrate includes forming a flexible substrate from a material selected from the group including plastic and metal films.
- 10. (Original) The method of claim 1 wherein forming the first rigid support substrate with trenches includes:

forming a rigid support substrate with a top surface;

forming a photoresist pattern with openings exposing the underlying support substrate top surface;

etching the exposed support substrate top surface to form the trenches in the support substrate; and

removing the photoresist.

11. (Currently Amended) A method for mounting a flexible substrate in the fabrication of a liquid crystal display (LCD), the method comprising:

forming a first rigid support substrate;

distributing a first pattern of spacers, consisting of noncommunicating with spacer channels between the spacers, overlying the first <u>rigid</u> support substrate;

forming a first flexible substrate overlying the first pattern of spacers;

injecting adhesive into the spacer channels; and curing the adhesive to attach the first flexible substrate to the first <u>rigid</u> support substrate.

12. (Currently Amended) The method of claim 11 further comprising:

subsequent to additional LCD fabrication processes, detaching the first <u>rigid</u> support substrate, spacers, and adhesive from the first flexible substrate.

13. (Original) The method of claim 11 further comprising:

depositing a plurality of patterned integrated circuit films overlying the first flexible substrate, forming thin film transistors (TFTs); forming a liquid crystal (LC) layer overlying the TFTs; and, forming a color filter layer over the LC layer.

14. (Currently Amended) The method of claim 13 further comprising:

forming a second flexible substrate overlying the color filter;

distributing a second pattern of spacers, <u>consisting of non-communicating with</u> spacer channels between the spacers, overlying the second flexible substrate;

forming a second rigid support substrate overlying the second pattern of spacers;

injecting adhesive into the spacer channels; and curing the adhesive to attach the second flexible substrate to the second <u>rigid</u> support substrate.

- 15. (Original) The method of claim 11 wherein injecting adhesive into the spacer channels includes injecting the adhesive in a vacuum environment.
- 16. (Currently Amended) The method of claim 15 wherein distributing a pattern of spacers, consisting of non-communicating with spacer channels between the spacers includes forming spacer channels with at least one mouth; and

wherein injecting adhesive into spacer channels includes: creating a vacuum environment in the spacer channels; supplying adhesive to the at least one spacer channel mouth; returning the first rigid support substrate to ambient

pressure; and

in response to returning the first rigid support substrate to ambient pressure, pulling the adhesive into the spacer channels vacuum environment through the at least one mouth.

- 17. (Original) The method of claim 16 wherein returning the first rigid support substrate to ambient pressure includes supplying an N2 atmosphere at ambient pressure.
- 18. (Currently Amended) The method of claim 11 wherein forming the first rigid support substrate trenches includes forming a rigid support substrate from a material selected from the group including glass and plastic.
- 19. (Original) The method of claim 11 wherein forming the first flexible substrate overlying the pattern of spacers includes forming the first flexible substrate from a material selected from the group including plastic and metal films.
- 20. (Withdrawn)A structure to support a flexible substrate liquid crystal display (LCD) during fabrication, the structure comprising:

 a first rigid temporary support substrate with trenches;

 a first flexible substrate overlying the temporary support substrate; and

vacuum injected adhesive in the trenches to attach the first temporary rigid support substrate to the first flexible support substrate.

21. (Withdrawn) The structure of claim 20 further comprising:

integrated circuit (IC) films, formed into thin film transistors (TFTs), overlying the first flexible substrate.

- 22. (Withdrawn) The structure of claim 21 further comprising:
 - a liquid crystal (LC) layer overlying the TFTs;
 - a color filter overlying the LC layer.
- 23. (Withdrawn) The structure of claim 22 further comprising:
 - a second flexible substrate overlying the color filter;
- a second rigid temporary support substrate with trenches overlying the second flexible substrate; and,

vacuum injected adhesive in the second temporary support substrate trenches to attach the second temporary rigid support structure to the second flexible support structure.

- 24. (Withdrawn) The structure of claim 20 wherein the first temporary support substrate is made from a material selected from the group including glass and plastic.
- 25. (Withdrawn)The structure of claim 20 wherein the first flexible substrate is made from a material selected from the group including plastic and metal films.
- 26. (Withdrawn) A structure to support a flexible substrate liquid crystal display (LCD) during fabrication, the structure comprising:
 - a first rigid temporary support substrate;
- a first temporary pattern of spacers, with spacer channels between the spacers, overlying the first temporary support substrate;

a first flexible substrate overlying the first temporary pattern of spacers; and

vacuum injected adhesive in the spacer channels to attach the first temporary support substrate to the first flexible substrate.

27. (Withdrawn) The structure of claim 26 further comprising:

integrated circuit (IC) films, formed into thin film transistors (TFTs), overlying the first flexible substrate.

28. (Withdrawn) The structure of claim 27 further comprising:

a liquid crystal (LC) layer overlying the TFTs; and, a color filter overlying the LC layer.

29. (Withdrawn) The method of claim 28 further comprising:

a second flexible substrate overlying the color filter;
a second temporary pattern of spacers, with spacer channels
between the spacers, overlying the second flexible substrate;

a second rigid temporary support substrate overlying the second temporary pattern of spacers; and,

vacuum injected adhesive in the spacer channels to attach the second temporary support substrate to the second flexible substrate.

- 30. (Withdrawn)The structure of claim 26 wherein the first temporary support substrate is made from a material selected from the group including glass and plastic.
- 31. (Withdrawn) The structure of claim 26 wherein the first flexible substrate is made from a material selected from the group including plastic and metal films.